



US00D845794S

(12) **United States Design Patent** (10) **Patent No.:** **US D845,794 S**
Wieser (45) **Date of Patent:** **** Apr. 16, 2019**

(54) **SURVEYING INSTRUMENT**

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(73) Assignee: **Leica Geosystems AG**, Heerbrugg (CH)

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(**) Term: **15 Years**

(Continued)

(21) Appl. No.: **29/596,907**

Primary Examiner — Leanne Was-Englehart

(22) Filed: **Mar. 13, 2017**

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(30) **Foreign Application Priority Data**

(57) **CLAIM**

Nov. 9, 2016 (CH) DM/093679
Nov. 9, 2016 (EM) DM/093679
Nov. 9, 2016 (LI) DM/093679

The ornamental design for a surveying instrument, as shown.

(51) **LOC (11) Cl.** **10-04**

(52) **U.S. Cl.**
USPC **D10/66**

DESCRIPTION

(58) **Field of Classification Search**
USPC D10/65, 66, 69, 70, 75
CPC . G01C 1/00–1/14; G01C 15/002; G01C 3/08;
G02B 7/32; G01D 5/24438; G01S 17/89
See application file for complete search history.

This application is related to a U.S. design application Ser. No. 29/596,908 entitled “Surveying Instrument” that claims the same priority.

This application is related to a U.S. design application Ser. No. 29/596,928 entitled “Case for Surveying Instrument” that claims the same priority.

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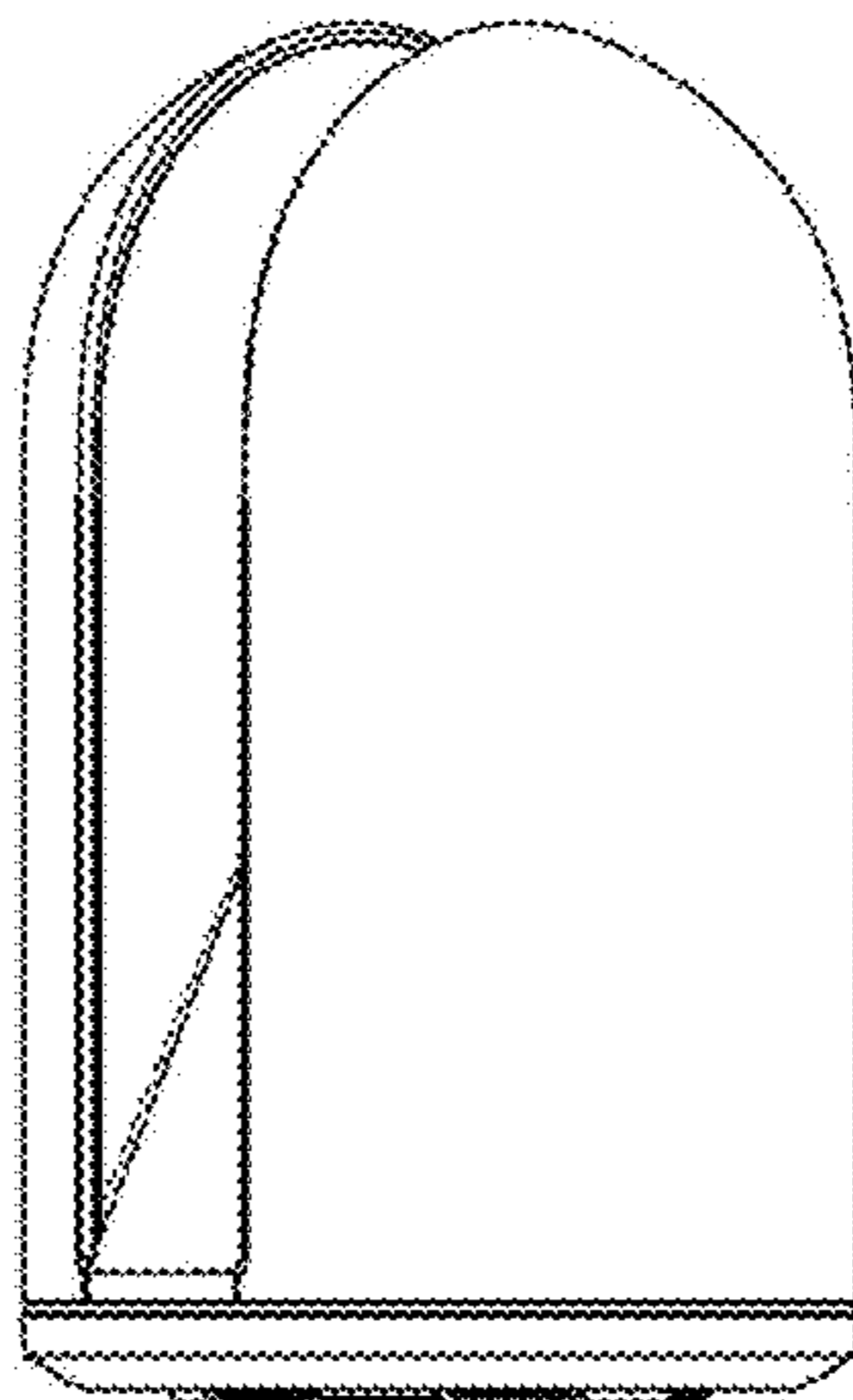
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FIG. 1 is a front perspective view of a surveying instrument. FIG. 2 is a front elevation view of the surveying instrument. FIG. 3 is a left elevation view of the surveying instrument. FIG. 4 is a rear elevation view of the surveying instrument. FIG. 5 is a right elevation view of the surveying instrument. FIG. 6 is a top view of the surveying instrument; and, FIG. 7 is a bottom view of the surveying instrument.

The broken lines depict portions of the surveying instrument that form no part of the claimed design.

(Continued)

1 Claim, 7 Drawing Sheets



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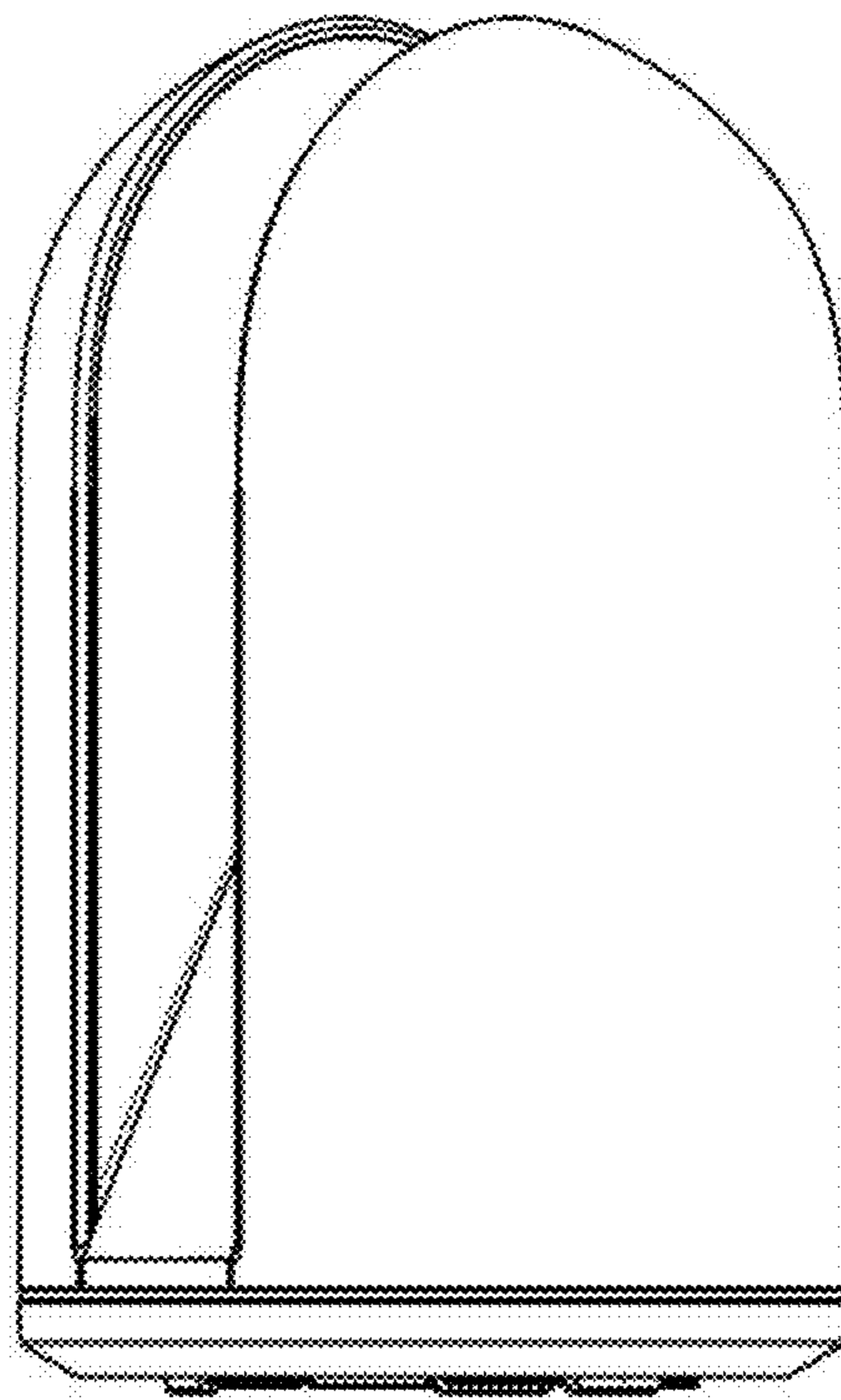


FIG. 1

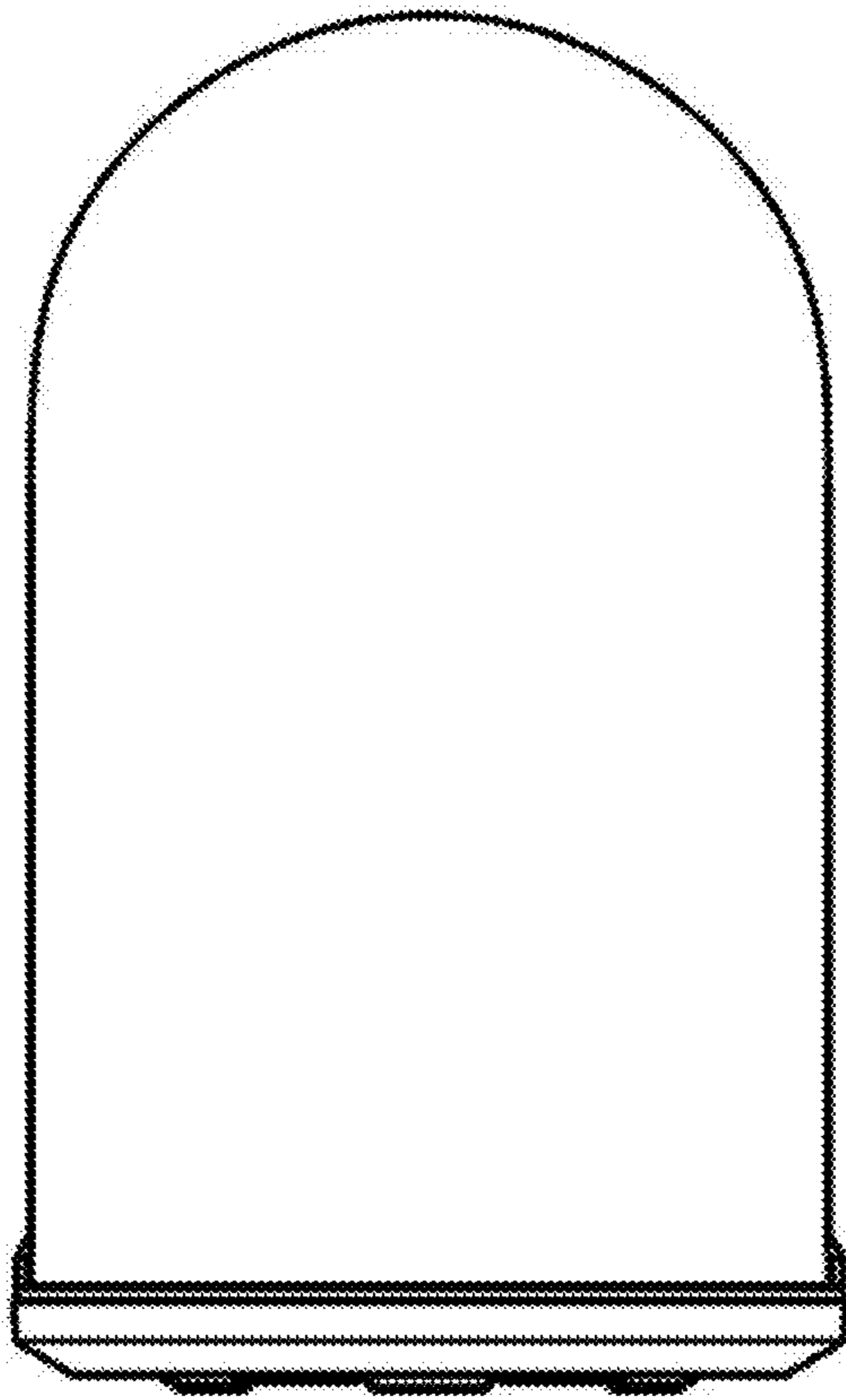


FIG. 2

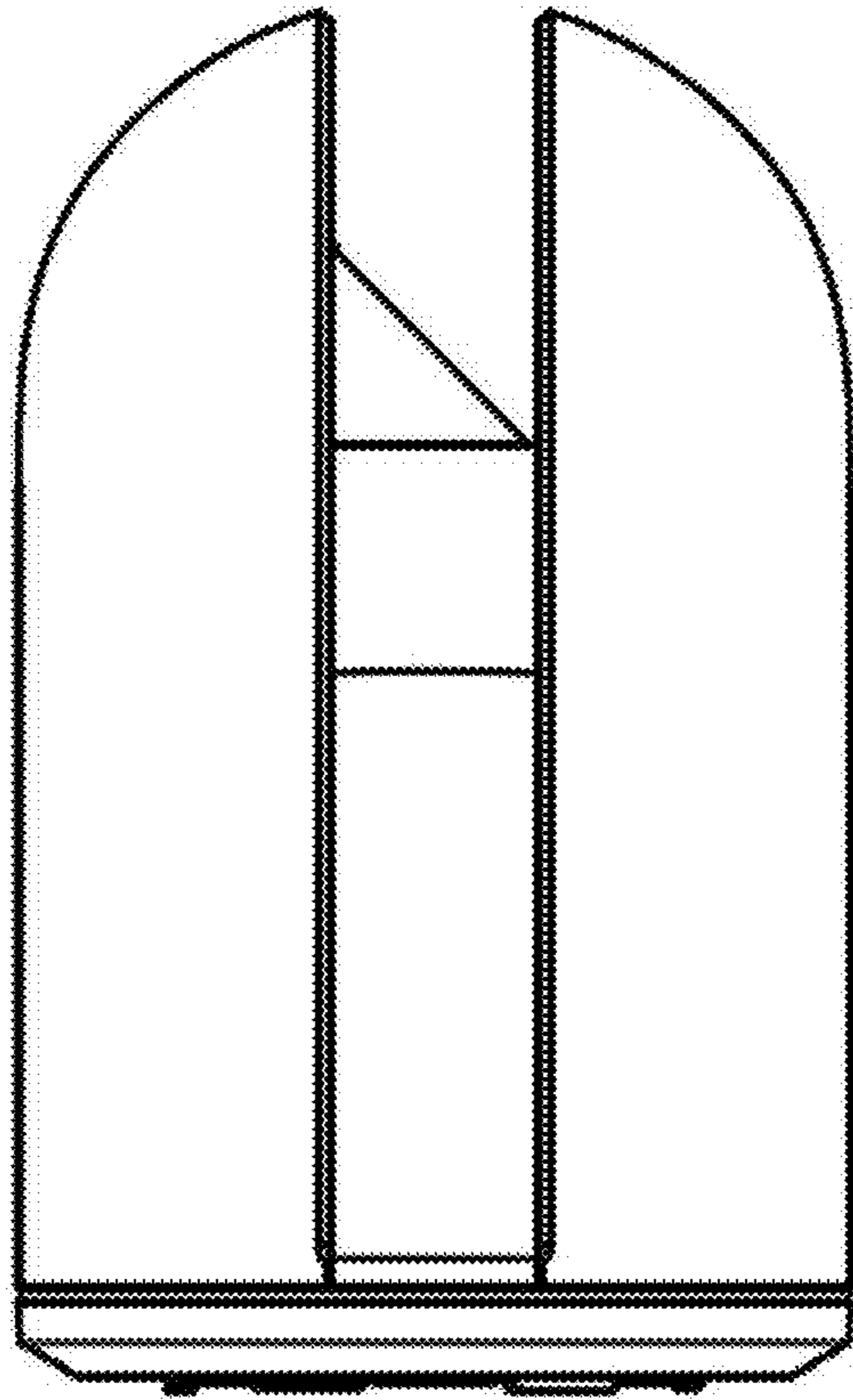


FIG. 3

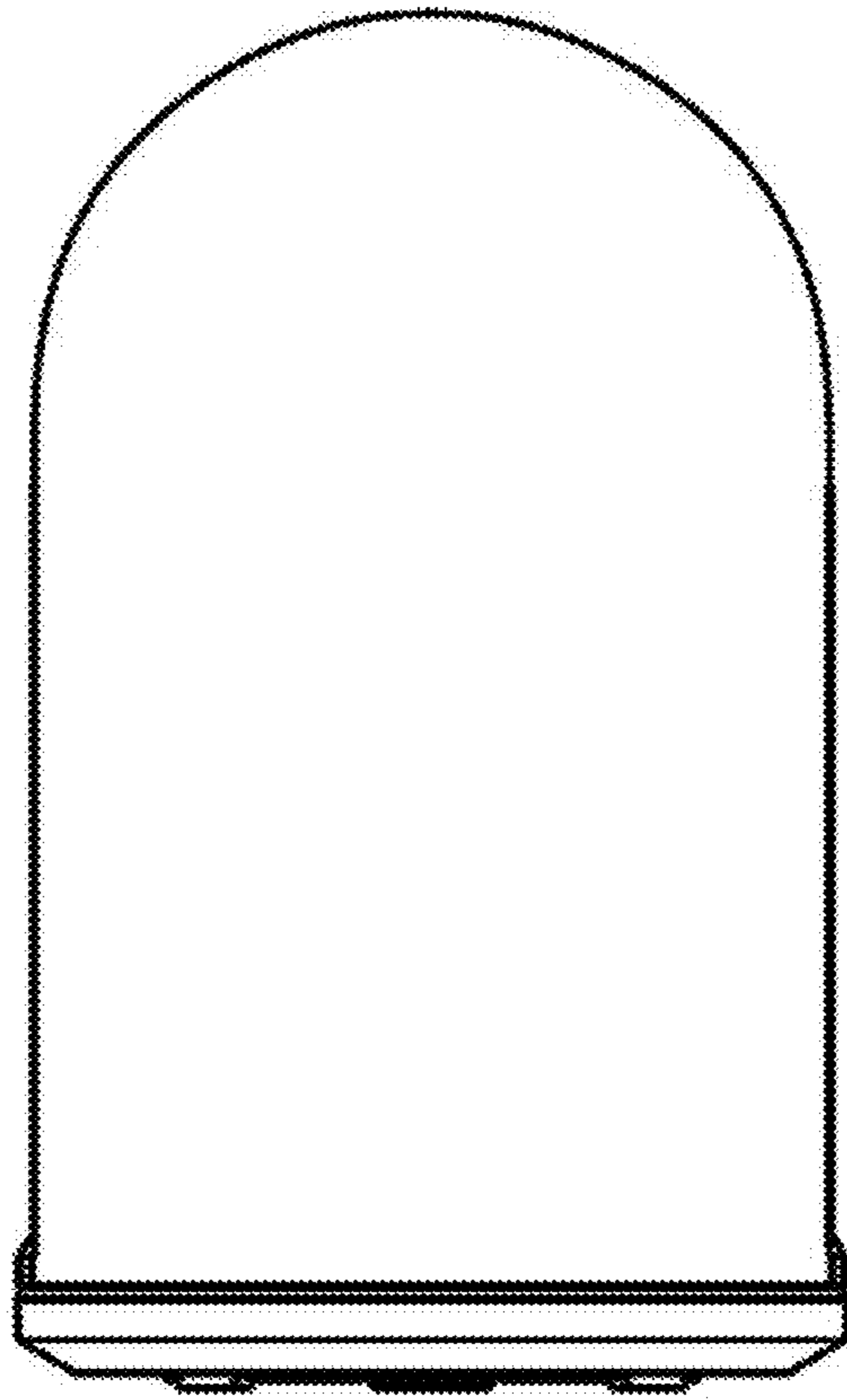


FIG. 4

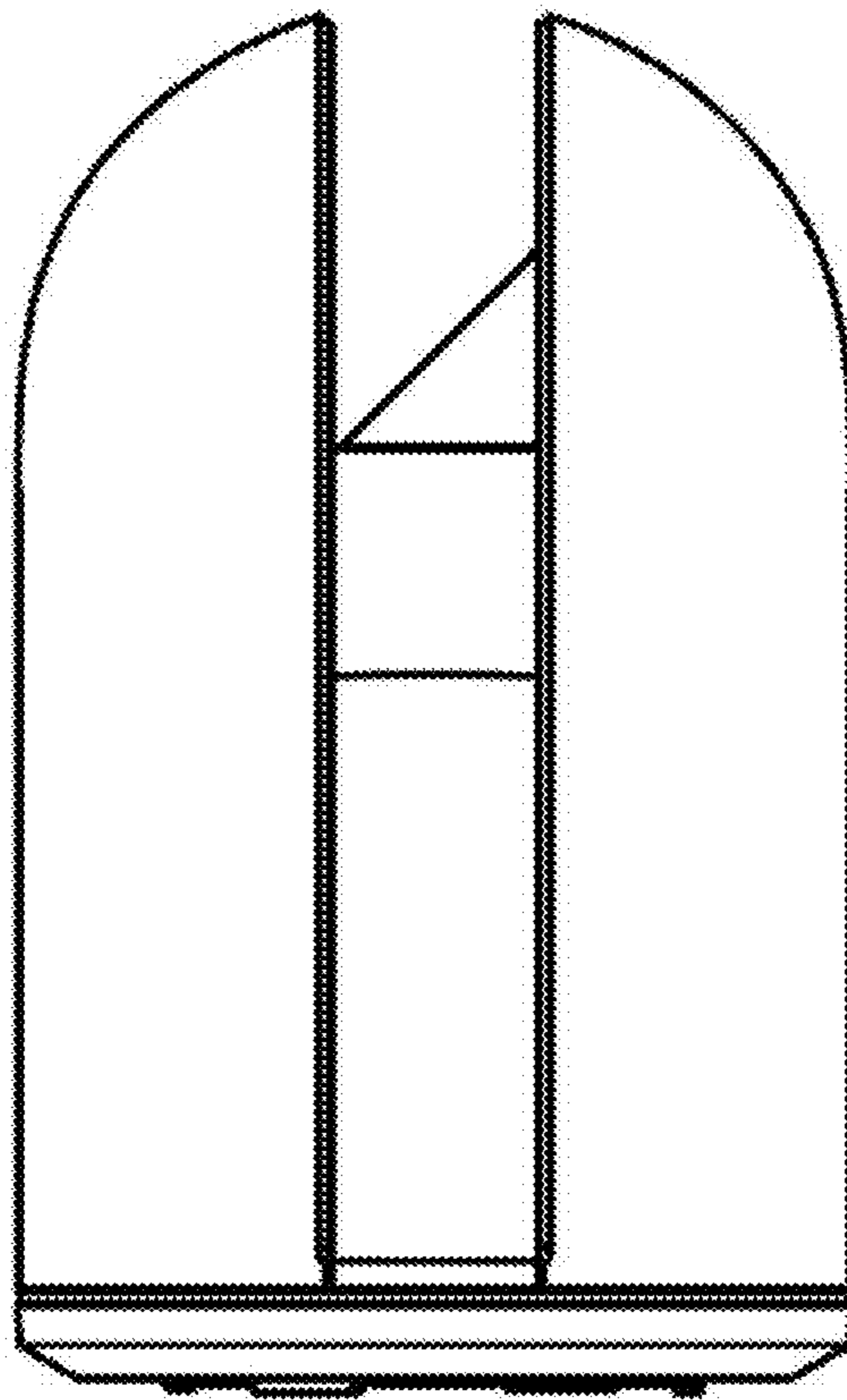


FIG. 5

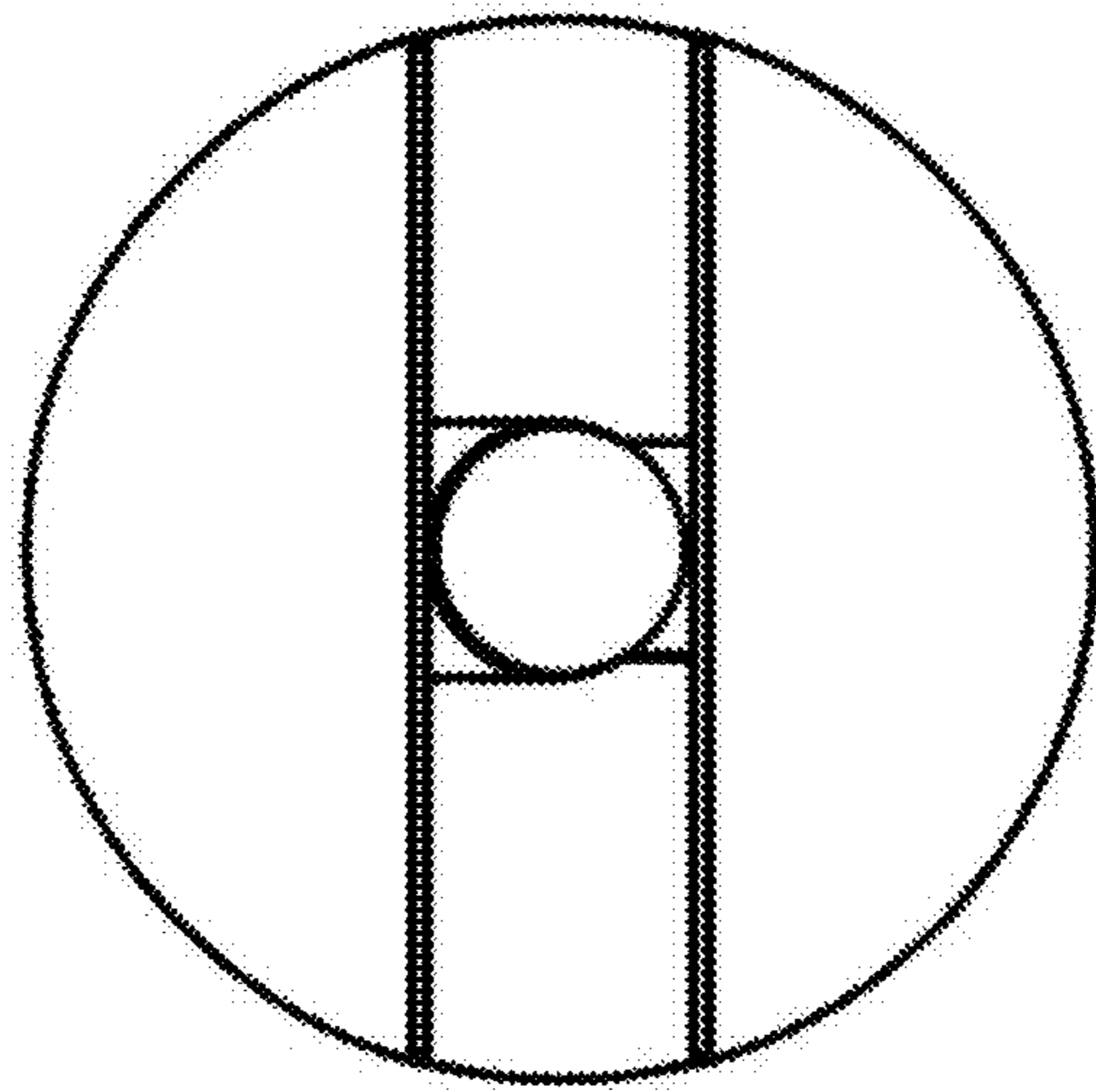


FIG. 6

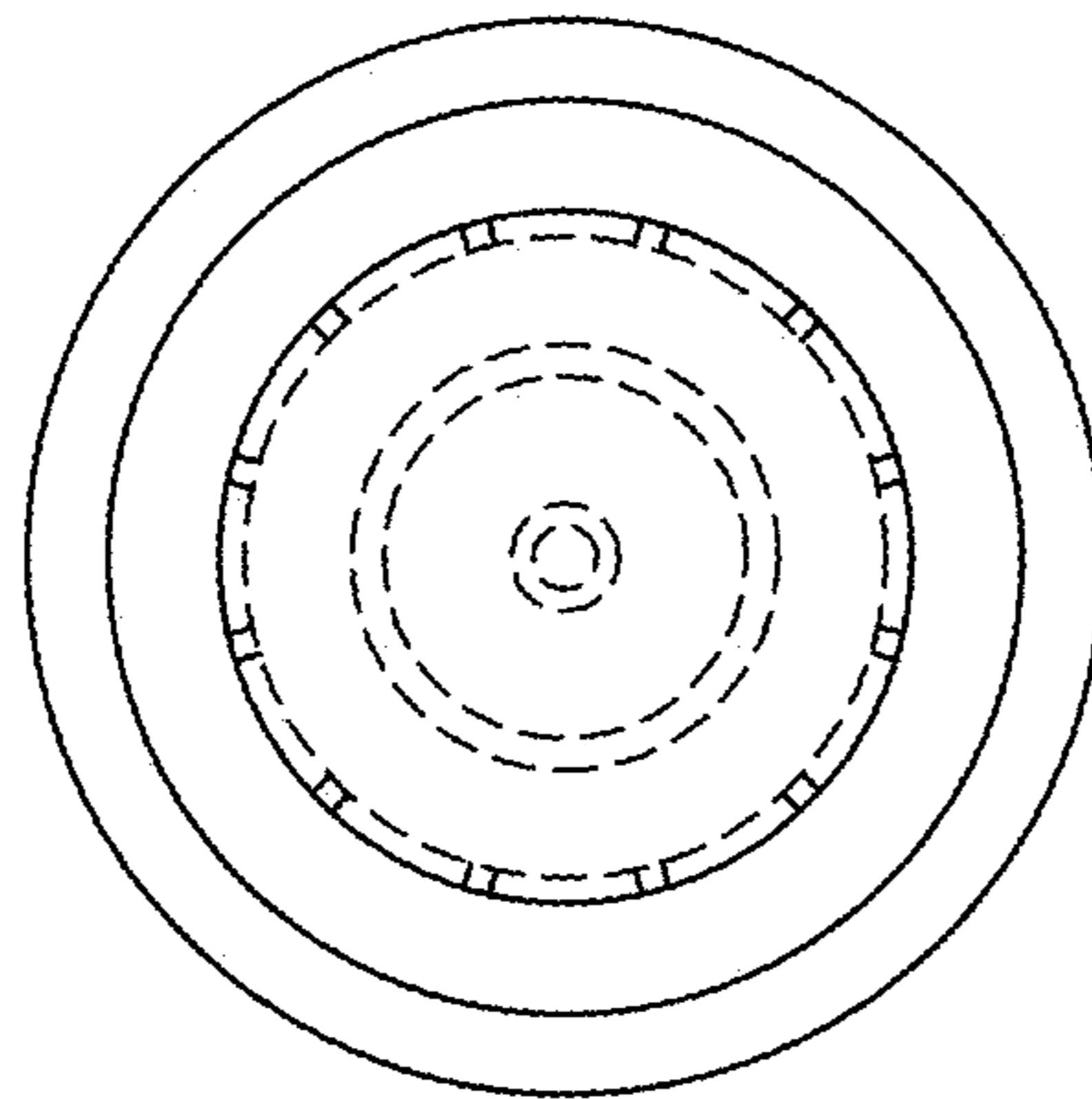


FIG. 7